

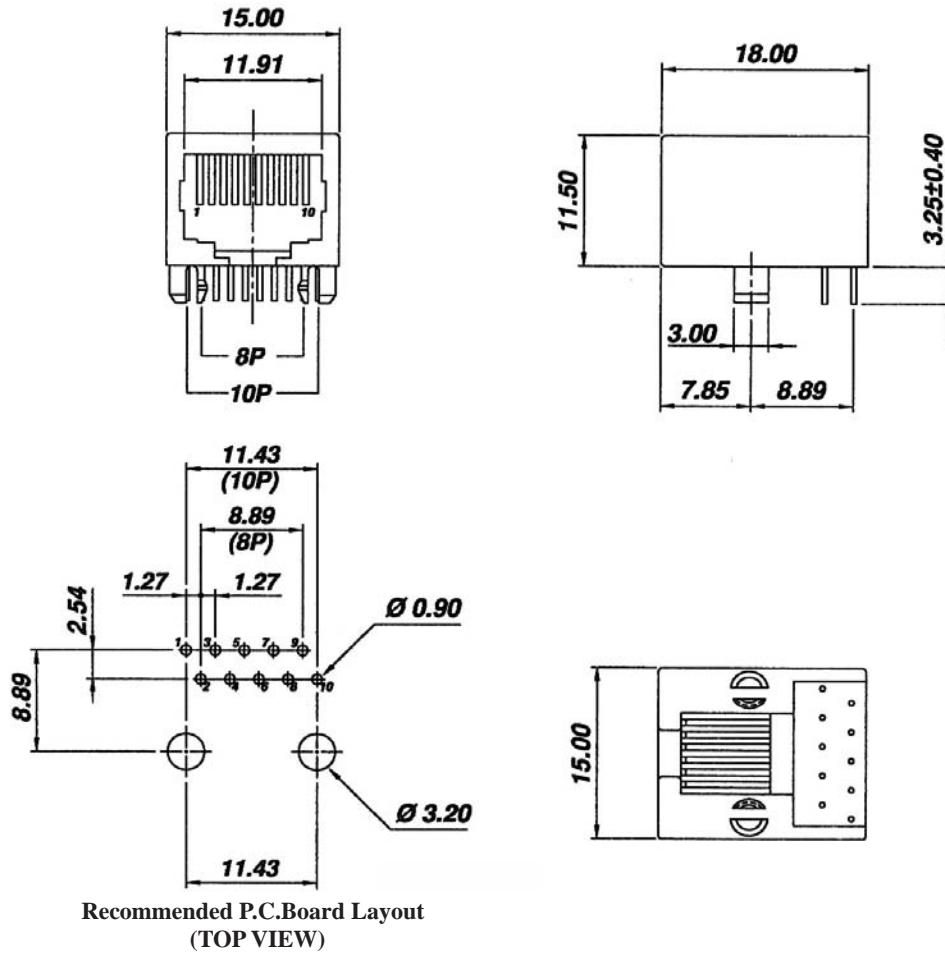
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N MJLA - $\frac{00}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: P/N MJLAHT-00xB for High Temp. Version

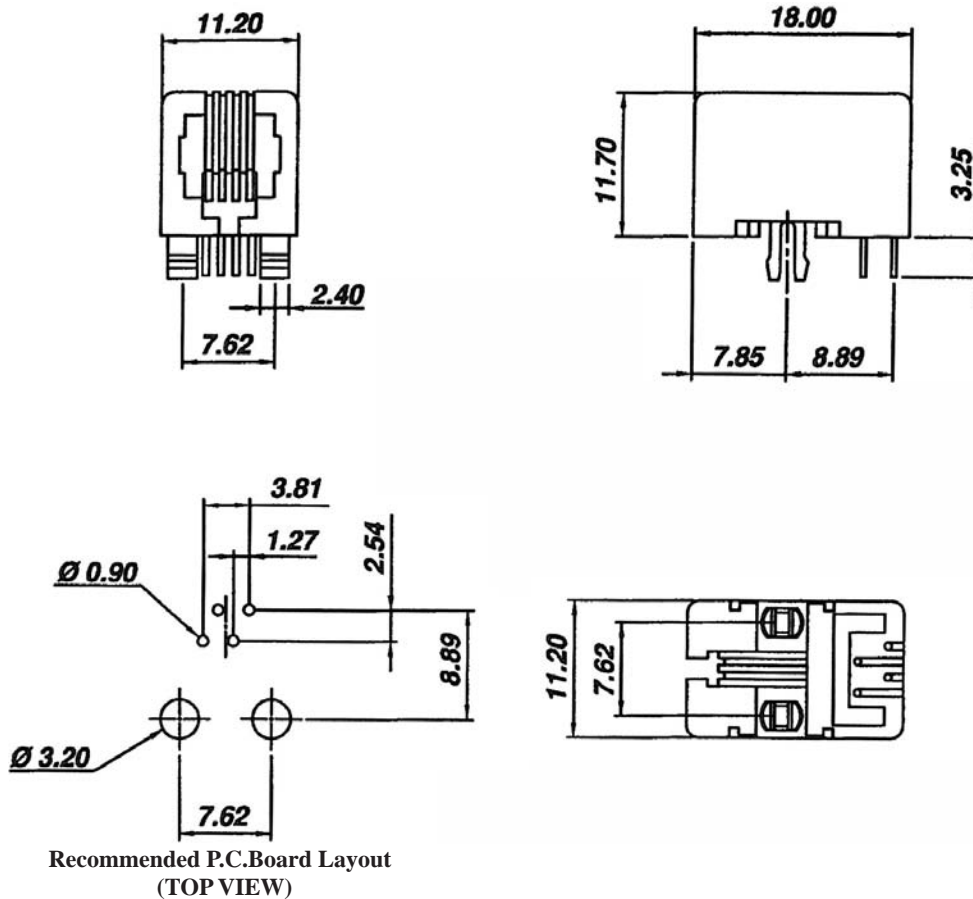
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

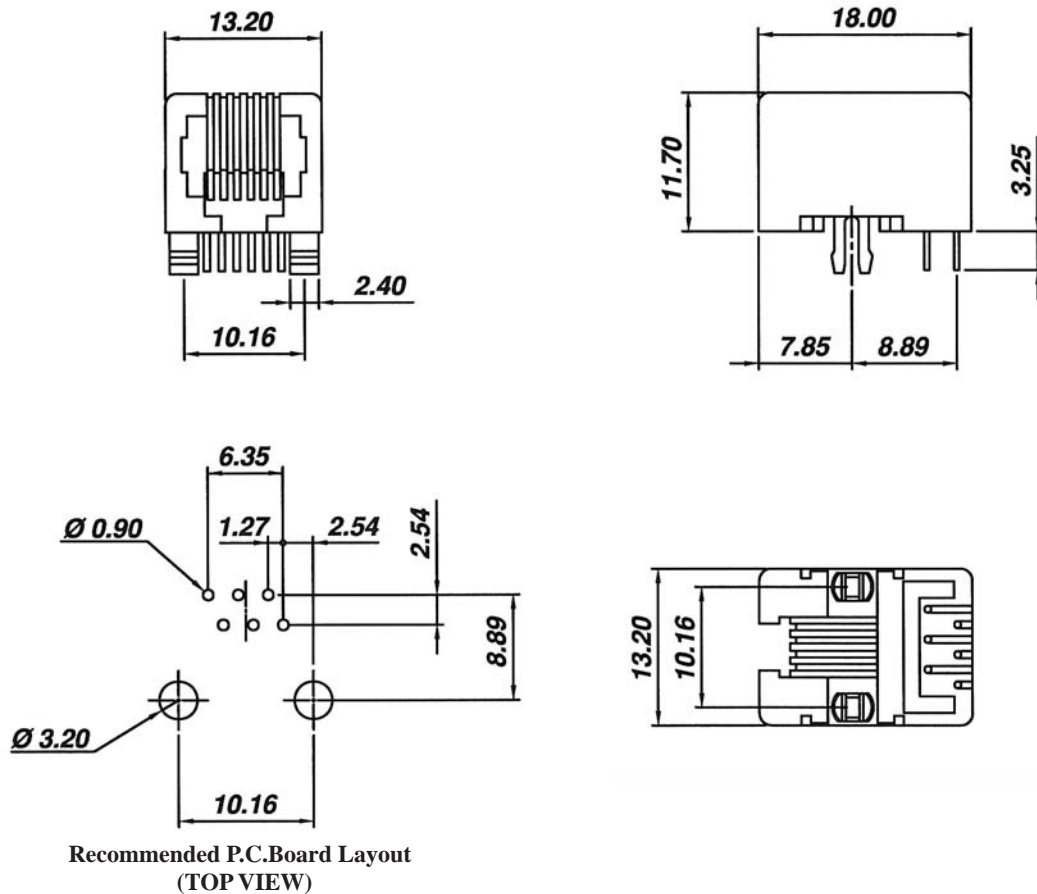
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{x x x}{T} B$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: PEG SPACING= 10.16MM

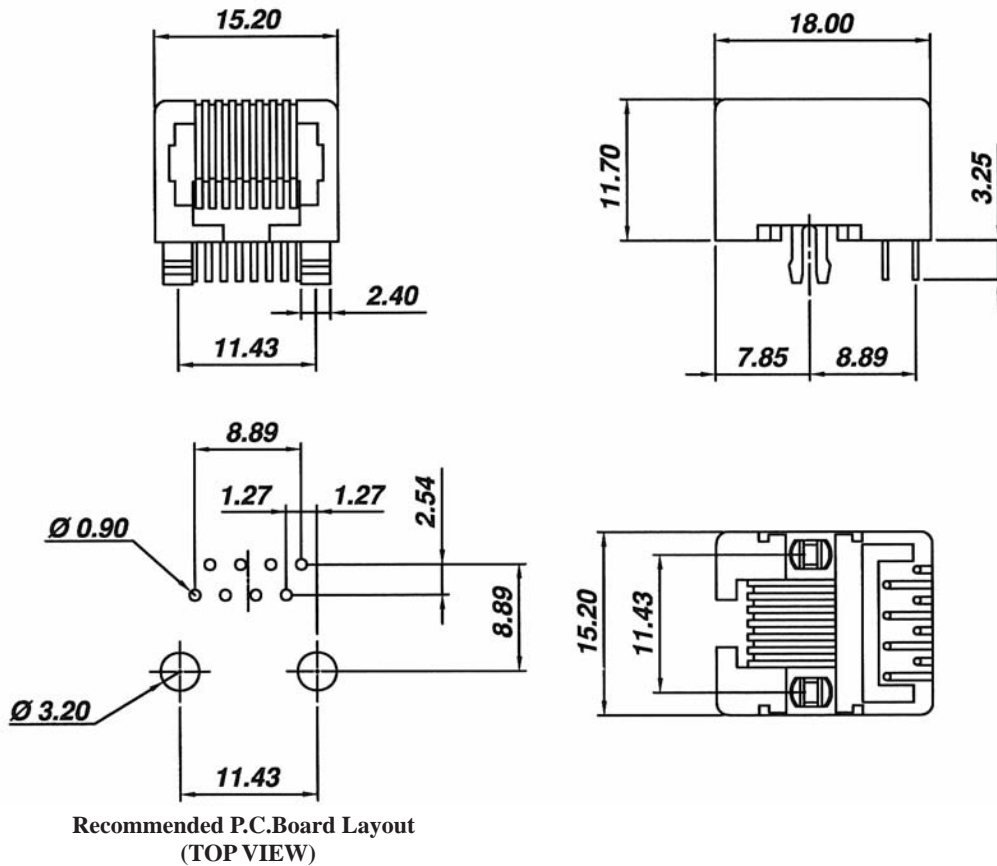
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD